

CLAIMS

1. A conductive particle,
which comprises a base particle and a conductive
5 layer formed on a surface of said base particle,
said conductive layer having a non-crystal nickel
plating layer in contact with the surface of said base
particle and a crystal nickel plating layer, and
a proportion of a nickel crystal grain aggregate
10 oriented in a nickel (111) plane derived from an integrated
intensity ratio in X-ray diffraction measurement being 80%
or more.
2. The conductive particle according to claim 1,
15 wherein a phosphorus content of the non-crystal
nickel plating layer is 10 to 18% and a phosphorus content
of the crystal nickel plating layer is 1 to 8%.
3. The conductive particle according to claim 1 or 2,
20 wherein the conductive layer contains bismuth and/or
thallium in an amount of 1000 ppm or less.
4. The conductive particle according to claim 1, 2
or 3,
25 wherein the conductive layer has a projection on the
surface thereof.
5. The conductive particle according to claim 4,
wherein the projection has a core material.
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6. The conductive particle according to claim 5,
wherein 80% or more of the core material is in
contact with the base particle or is in a distance of 5 nm
or less from said base particle.
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7. The conductive particle according to claim 1, 2,
3, 4, 5 or 6,

wherein a gold layer is further formed on the surface
of the conductive layer.

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8. A method of producing the conductive particle
according to claim 1, 2, 3, 4, 5, 6 or 7, comprising:

a step 1 of providing a catalyst for the surface of
the base particle;

10 a step 2 of using a nickel plating solution
containing at least one complexing agent selected from the
group consisting of citric acid, malic acid, succinic acid,
propionic acid, lactic acid and acetic acid, and salts
thereof and forming the non-crystal nickel plating layer on
15 the surface of said base particle by adjusting a pH to 4.9
or less in a nickel plating reaction; and

a step 3 of using a nickel plating solution
containing at least one complexing agent selected from the
group consisting of citric acid, malic acid, succinic acid,
20 propionic acid, lactic acid and acetic acid, and salts
thereof and forming the crystal nickel plating layer by
adjusting a pH to 7.2 to 9 in a nickel plating reaction.

9. An anisotropic conductive material,
25 which is obtained by dispersing the conductive
particle according to claim 1, 2, 3, 4, 5, 6 or 7 in a
resin binder.